



Surface Mount General Purpose Silicon Rectifiers

Reverse Voltage - 50 to 1000 V

Forward Current - 3 A

FEATURES

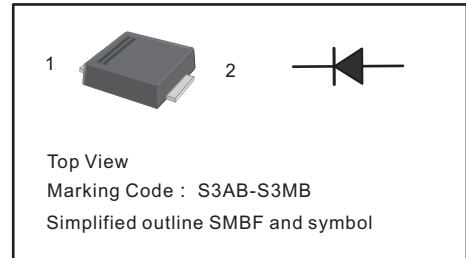
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S3ABF	S3BBF	S3DBF	S3GBF	S3JBF	S3KBF	S3MBF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 115\text{ }^\circ\text{C}$	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	80							A
Maximum Instantaneous Forward Voltage at 3 A	V_F	1.1							V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5 150							μA
Typical Junction Capacitance ⁽¹⁾	C_j	35							pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$ $R_{\theta JC}$	45 15							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



Fig.1 Forward Current Derating Curve

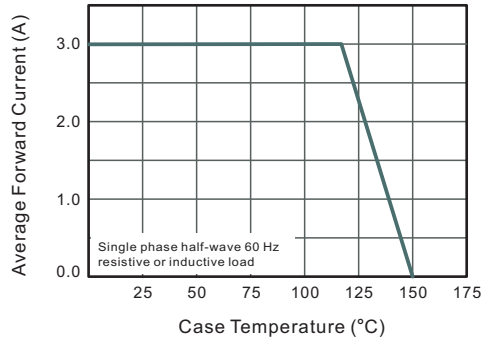


Fig.2 Typical Reverse Characteristics

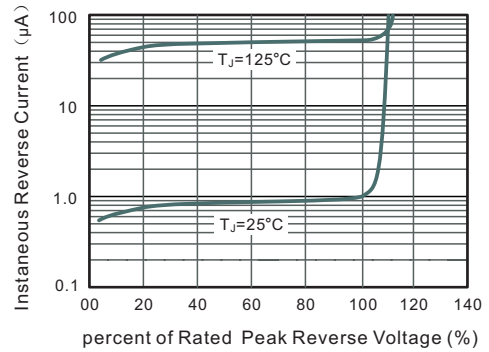


Fig.3 Typical Forward Characteristic

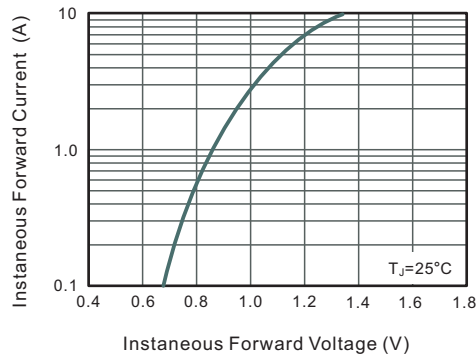


Fig.4 Typical Junction Capacitance

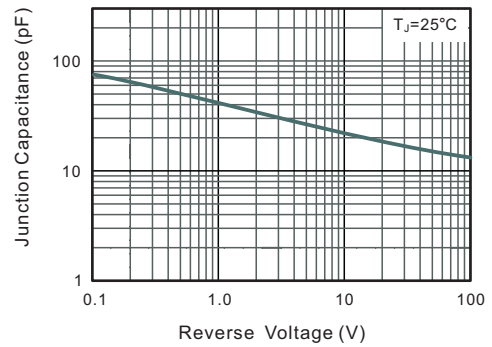
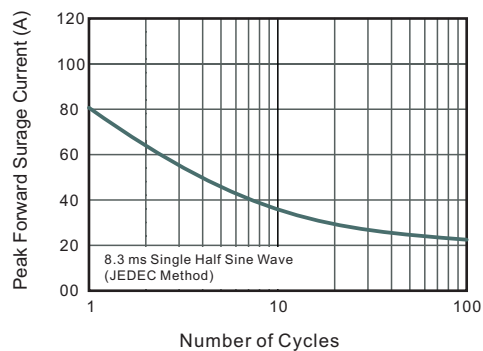


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

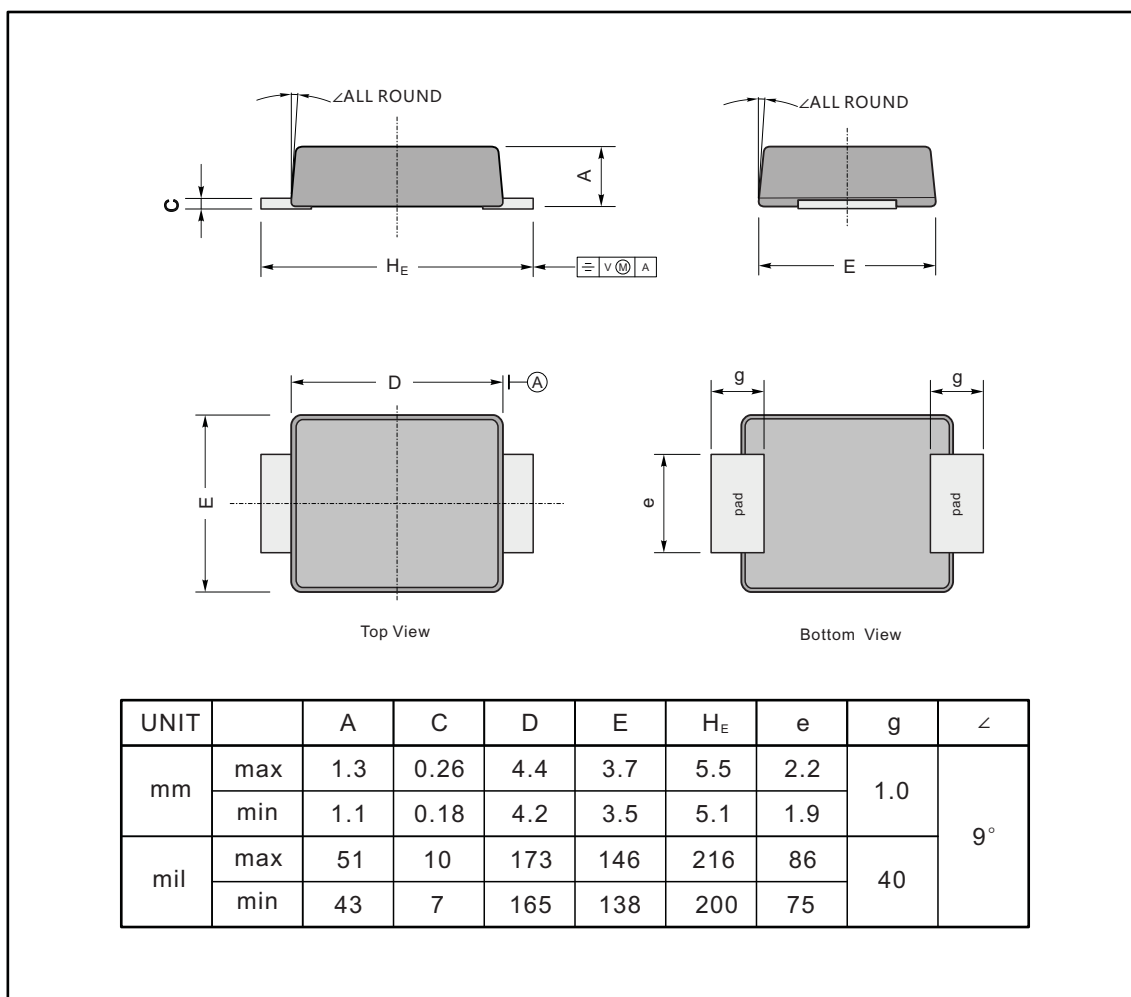




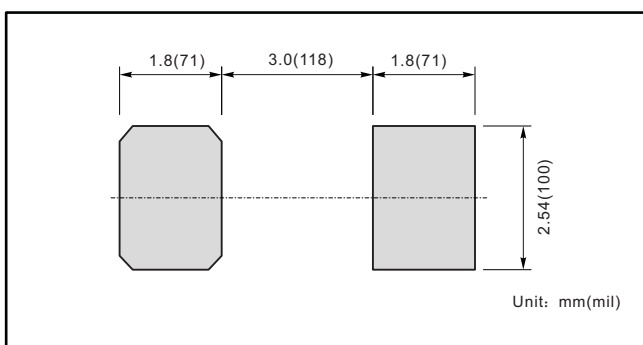
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMBF



The recommended mounting pad size



Marking

Type number	Marking code
S3ABF	S3AB
S3BBF	S3BB
S3DBF	S3DB
S3GBF	S3GB
S3JBF	S3JB
S3KBF	S3KB
S3MBF	S3MB

单击下面可查看定价，库存，交付和生命周期等信息

[>>JINGDAO\(晶导微\)](#)